Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP ProDesk 680 G4 MT

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [x] snaps [ ] adhesive [ ] other. Explain ______ ______; NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td></td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>PSU</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

#### 3.1
List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Loose the screw and remove access panel.(see Figure 1 below)
2. Disconnect ODD/HDD power cable and SATA cable from ODD/HDD.(see Figure 2- 5 below)
3. Remove the driver cage from chassis.(see Figure 6 below)
4. Remove ODD/HDD from driver cage.(see Figure 7-10 below)
5. Disconnect all cables from the MB.(see Figure 11 below)
6. Remove the heatsink from MB.(see Figure 12 below)
7. Separate the fan from CPU heatsink. (see Figure 13-14 below)
8. Remove the Memory card from the MB.(see Figure 15 below)
9. Remove the CPU from the MB.(see Figure 16-17 below)
10. Remove the battery from the MB .(see Figure 18 below)
11. Remove M/B from chassis.(see Figure 19-21 below)
12. Remove Speaker/system fan from chassis.(see Figure 22-23 below)
13. Remove PSU from chassis.(see Figure 24-26 below)
14. Separate PSU cover/fan and remove the Electrolytic Capacitors.(see Figure 27-34 below)

#### 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Loose thumb screw and remove access panel

Figure 2 Disconnect ODD power cable from ODD

Figure 3 Disconnect SATA cable from ODD

Figure 4 Disconnect HDD Power cable from HDD

Figure 5 Disconnect SATA cable from HDD

Figure 6 Remove the driver cage from chassis

HPI instructions for this template are available at EL-MF877-01
Figure 7 Press the ODD’s latch on ODD cage

Figure 8 Remove the ODD from ODD cage

Figure 9 Use T-15 screwdriver to loose the screws of HDD from cage

Figure 10 Remove the HDD from HDD cage

Figure 11 Disconnect all cables from the MB

Figure 12 Use T-15 screwdriver to loose the screws and remove heat sink
Figure 13 Use PH1 screwdriver to loose the screws and remove the fan

Figure 14 Separate the fan from CPU heat sink

Figure 15 Remove the Memory card from the board

Figure 16 Rotate the handle and open it up

Figure 17 Remove the CPU from the board

Figure 18 Remove the battery from the system board
Figure 19 Use T-15 screwdriver to loose the screws of MB from board

Figure 20 Remove front panel from chassis

Figure 21 Remove MB from chassis

Figure 22 Use T-15 screwdriver to loose the screws of speaker and remove it

Figure 23 Use PH1 screwdriver to loose the screws of system fan and remove it

Figure 24 Use micro shear 170II to cut the cable ties from chassis front wall

HPI instructions for this template are available at EL-MF877-01
Figure 25 Use T-15 screwdriver to loose the screws of PSU

Figure 26 Press PSU latch and remove it

Figure 27 Remove screw for bottom

Figure 28 Remove screw for top

Figure 29 Remove cover

Figure 30 Remove FG screw

HPI instructions for this template are available at EL-MF877-01
Figure 31 Disconnect fan connector and inlet connector.

Figure 32 Remove PCB1 screw

Figure 33 Remove AC inlet & Fan screw

Figure 34 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it.